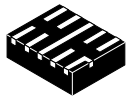


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

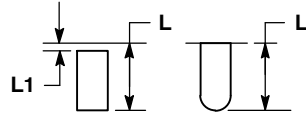
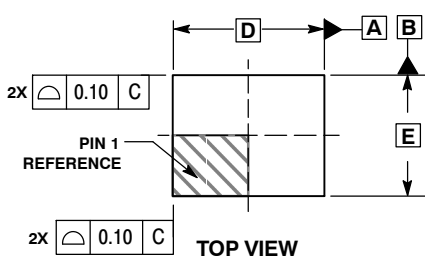
ON Semiconductor®



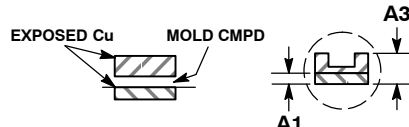
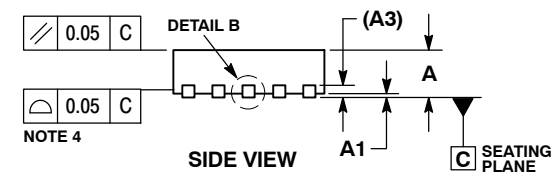
SCALE 4:1

WDFN10 2.5x2, 0.5P
CASE 511BM-01
ISSUE O

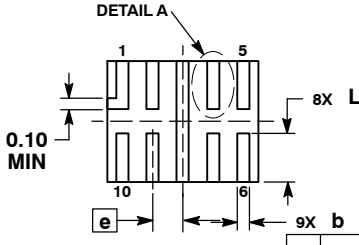
DATE 29 JUN 2010



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



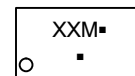
MILLIMETERS		
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.15	0.25
D	2.50	BSC
E	2.00	BSC
e	0.50	BSC
L	0.70	0.90
L1	0.05	0.15



⊕	0.10 (M)	C	A	B
	0.05 (M)	C		

NOTE 3

GENERIC MARKING DIAGRAM*

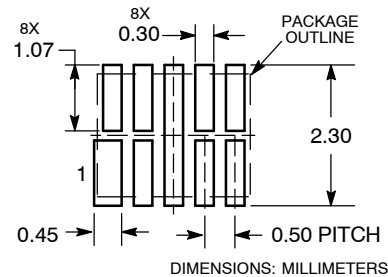


- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT



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NEW STANDARD:		
DESCRIPTION:	WDFN10 2.5X2, 0.5P	PAGE 1 OF 2

